



DMS2120LFWB

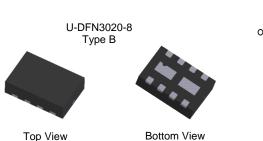
P-CHANNEL ENHANCEMENT MODE MOSFET WITH INTEGRATED SBR® SUPER BARRIER RECTIFIER

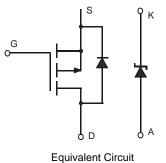
Features

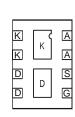
- Low On-Resistance
 - $95m\Omega @V_{GS} = -4.5V$
 - 120mΩ @V_{GS} = -2.5V
 - $150m\Omega$ (typ) @V_{GS} = -1.8V
- Low Gate Threshold Voltage, -1.3V Max
- · Fast Switching Speed
- Low Input/Output Leakage
- Incorporates Low V_F Super Barrier Rectifier (SBR)
- Low Profile, 0.5mm Max Height
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: U-DFN3020-8 Type B
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish NiPdAu annealed over Copper leadframe.
 Solderable per MIL-STD-202, Method 208 ⁶⁴
- Weight: 0.011 grams (approximate)







Bottom View Pin Configuration

Ordering Information (Note 4)

Part Number	Case	Packaging
DMS2120LFWB-7	DFN3020B-8	3000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com.

Marking Information

MF YM ● MF = Product Type Marking Code YM = Date Code Marking Y = Year (ex: V = 2008) M = Month (ex: 9 = September)

Date Code Key

Year	2008	2009	201	10	2011	2012	2013	2014	20)15	2016	2017
Code	V	W	X		Υ	Z	Α	В	(С	D	Е
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



Maximum Ratings – TOTAL DEVICE (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P_{D}	1.5	W
Thermal Resistance, Junction to Ambient	$R_{ hetaJA}$	85	°C/W
Operating and Storage Temperature Range	TJ, T _{STG}	-55 to +150	°C

Maximum Ratings - P-CHANNEL MOSFET - Q1 (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Drain-Source Voltage	V_{DSS}	-20	V
Gate-Source Voltage	V _{GSS}	±12	V
Drain Current (Note 5)	I _D	-2.9	А
Pulsed Drain Current (Note 6)	I _{DM}	-10	А

Maximum Ratings - SBR - D1 (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	20	V
RMS Reverse Voltage	V _{R(RMS)}	14	V
Average Rectified Output Current	Io	1	А
Non-Repetitive Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load	I _{FSM}	3	А

Electrical Characteristics - P-CHANNEL MOSFET - Q1 (@T_A = +25°C, unless otherwise specified.)

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Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	-20	_	_	V	$V_{GS} = 0V, I_D = -250\mu A$	
Zero Gate Voltage Drain Current	I _{DSS}	_		-1	μΑ	$V_{DS} = -20V, V_{GS} = 0V$	
Gate-Source Leakage	looo	_		±100	nA	$V_{GS} = \pm 8V$, $V_{DS} = 0V$	
0	I _{GSS}	_		±800	ш	$V_{GS} = \pm 12V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)	ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	$V_{GS(th)}$	-0.45		-1.3	>	$V_{DS} = V_{GS}, I_D = -250 \mu A$	
	R _{DS} (ON)	_	70	95	$m\Omega$	$V_{GS} = -4.5V$, $I_D = -2.8A$	
Static Drain-Source On-Resistance		_	84	120		$V_{GS} = -2.5V$, $I_D = -2.0A$	
		—	100	150		$V_{GS} = -1.8V, I_D = -1.0A$	
Forward Transfer Admittance	Y _{fs}	_	8	_	S	$V_{DS} = -5V$, $I_{D} = -2.8A$	
Diode Forward Voltage (Note 7)	V_{SD}	_	0.42	-1.2	V	$V_{GS} = 0V, I_{S} = -1.0A$	
DYNAMIC CHARACTERISTICS							
Input Capacitance	C _{iss}	_	632	_	pF	101/1/	
Output Capacitance	Coss	_	65	_	pF	V _{DS} = -10V, V _{GS} = 0V f = 1.0MHz	
Reverse Transfer Capacitance	Crss	_	54	_	pF	1 - 1.0ivii 12	

Electrical Characteristics – SBR – D1 (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	$V_{(BR)R}$	20	_	_	V	I _R = 1mA
Forward Voltage	V _F	_		0.45 0.52	V	I _F = 0.5A I _F = 1.0A
Reverse Current (Note 7)	I _R	_	_	80	μΑ	$V_R = 20V$

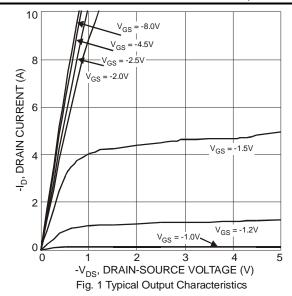
Notes: 5. Device mounted on FR-4 PCB, on minimum recommended, 2oz Copper pad layout.

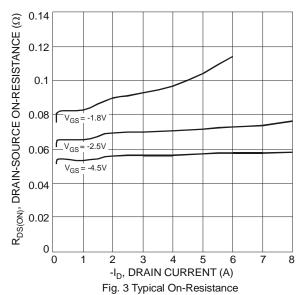
^{6.} Repetitive rating, pulse width limited by junction temperature.

^{7.} Short duration pulse test used to minimize self-heating effect.



Q1, P-CHANNEL MOSFET





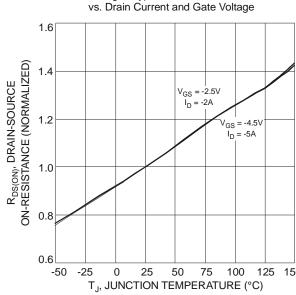


Fig. 5 On-Resistance Variation with Temperature

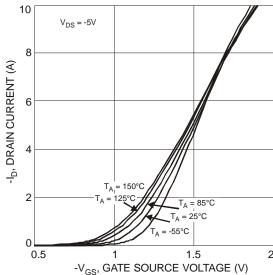


Fig. 2 Typical Transfer Characteristics

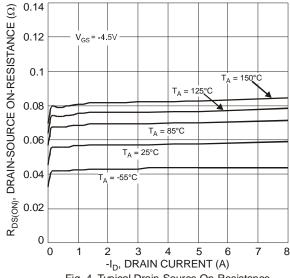


Fig. 4 Typical Drain-Source On-Resistance vs. Drain Current and Temperature

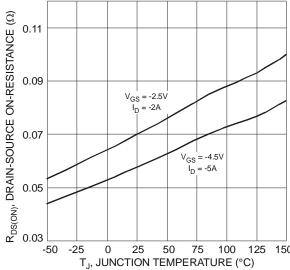
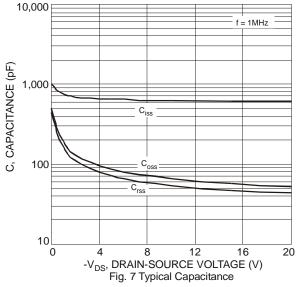
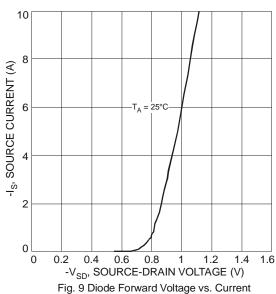


Fig. 6 On-Resistance Variation with Temperature







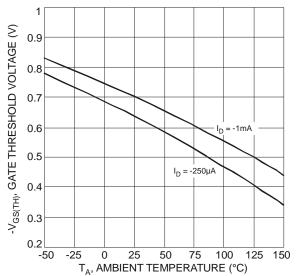
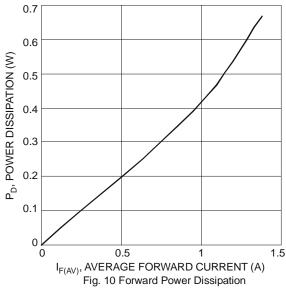
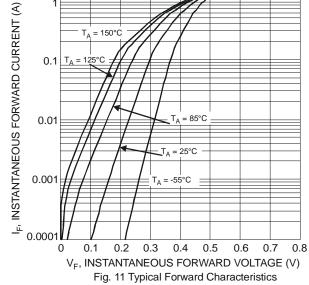


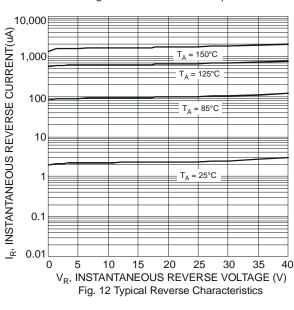
Fig. 8 Gate Threshold Variation vs. Ambient Temperature

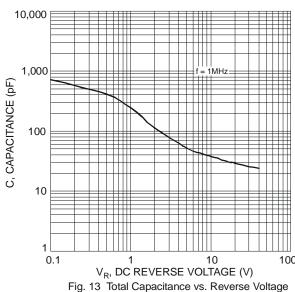


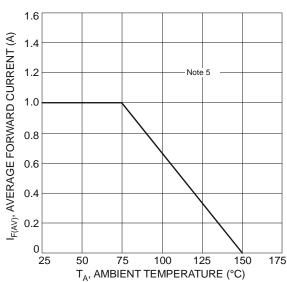
D1, SBR











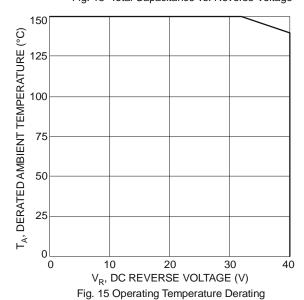
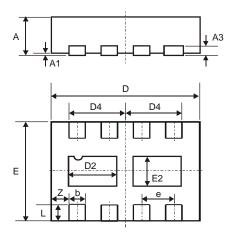


Fig. 14 Forward Current Derating Curve SBR is a registered trademark of Diodes Incorporated.



Package Outline Dimensions

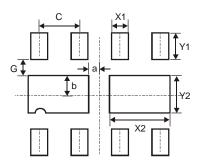
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



U-DFN3020-8									
	Type B								
Dim	Min	Max	Тур						
Α	0.77	0.83	0.80						
A1	0	0.05	0.02						
A3	-	-	0.15						
b	0.25	0.35	0.30						
D	2.95	3.075	3.00						
D2	0.82	1.02	0.92						
D4	1.01	1.21	1.11						
е	-	-	0.65						
Е	1.95	2.075	2.00						
E2	0.43	0.63	0.53						
L	0.25	0.35	0.30						
Z	-	-	0.375						
All	Dimens	sions in	mm						

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
а	0.09
b	0.365
С	0.65
G	0.285
X1	0.4
X2	1.12
Y1	0.5
Y2	0.73



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